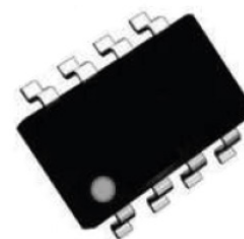
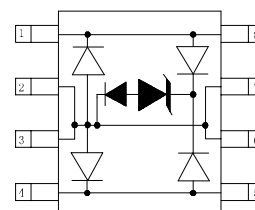


**Features**

- Low capacitance for high speed interfaces
- Ultra low leakage: nA level
- Low operating voltage
- Low clamping voltage
- Protects two lines in common and differential mode
- JEDEC SOP-8 package
- Complies with following standards:
  - IEC 61000-4-2 (ESD) immunity test
  - Air discharge: ±30kV
  - Contact discharge: ±30kV
  - IEC 61000-4-5 (Lightning) 100A (8/20µs)
- RoHS compliant



SOP-8



Schematic Diagram

**Applications**

- T1/E1 line cards
- T3/E3 and DS3 interfaces
- STS-1 interfaces
- 10/100/1000 base ethernet
- ISDN interfaces
- Low voltage interfaces

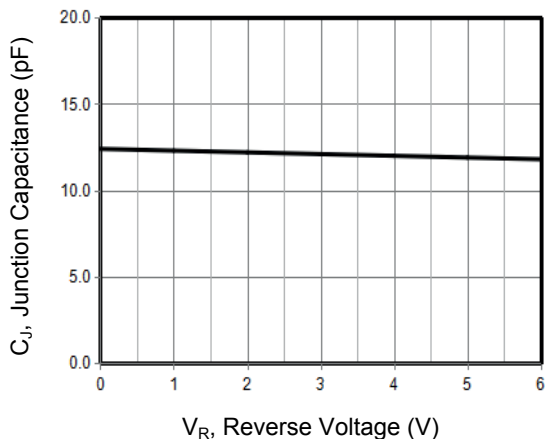
**Absolute Maximum Ratings** (T<sub>A</sub>=25°C unless otherwise specified)

Parameter	Symbol	Value	Unit
Peak Pulse Power (8/20µs)	P <sub>pk</sub>	2600	W
Peak Pulse Current (8/20µs)	I <sub>PP</sub>	100	A
ESD per IEC 61000-4-2 (Air)	V <sub>ESD</sub>	±30	kV
ESD per IEC 61000-4-2 (Contact)		±30	
Operating Temperature Range	T <sub>J</sub>	-55 to +125	°C
Storage Temperature Range	T <sub>stg</sub>	-55 to +150	°C

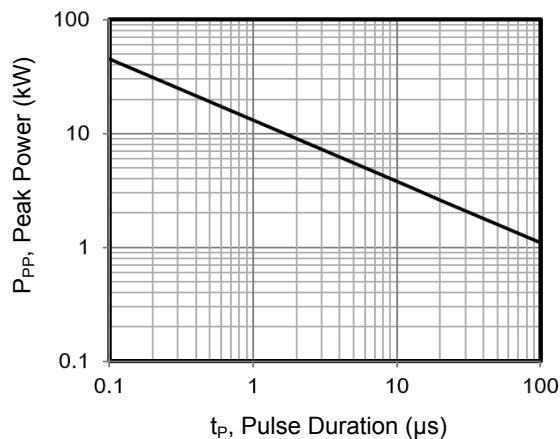
**Electrical Characteristics** (T<sub>A</sub>=25°C unless otherwise specified)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Reverse Working Voltage	V <sub>RWM</sub>	-	-	-	6	V
Breakdown Voltage	V <sub>BR</sub>	I <sub>T</sub> =1mA	6.8	-	-	V
Reverse Leakage Current	I <sub>R</sub>	V <sub>RWM</sub> =6V	-	-	25	µA
Clamping Voltage	V <sub>C</sub>	I <sub>PP</sub> =50A (8 x 20µs pulse), any I/O pin to ground	-	-	18	V
		I <sub>PP</sub> =100A (8 x 20µs pulse), any I/O pin to ground	-	-	26	V
Junction Capacitance	C <sub>J</sub>	V <sub>R</sub> =0V, f=1MHz, between I/O pins and ground	-	16	25	pF
		V <sub>R</sub> =0V, f=1MHz, between I/O pins	-	8	12	pF

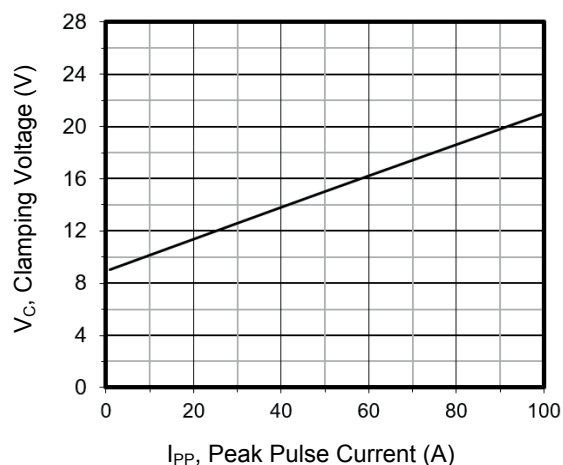
**Typical Performance Characteristic** ( $T_A=25^\circ\text{C}$  unless otherwise Specified)



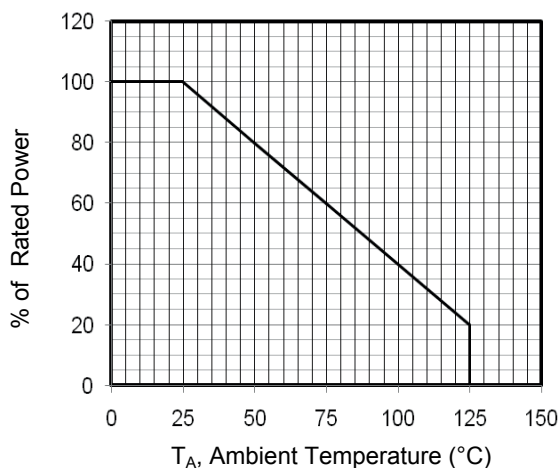
**Figure 1. Junction Capacitance vs. Reverse Voltage**



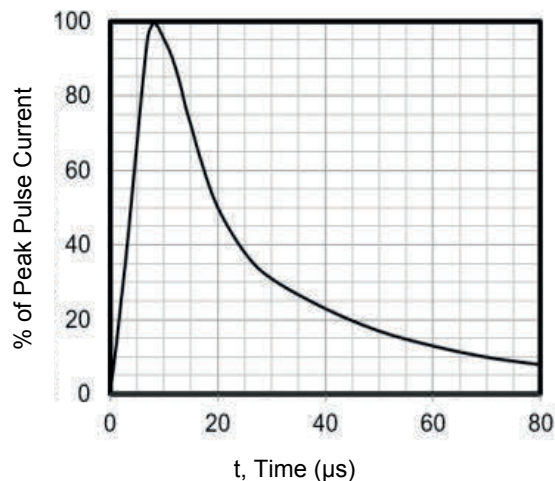
**Figure 2. Peak Pulse Power vs. Pulse Time**



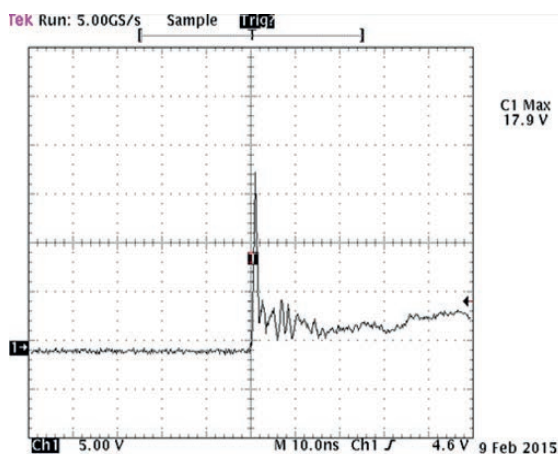
**Figure 3. Clamping Voltage vs. Peak Pulse Current**  
 $(t_p=8/20\mu\text{s})$



**Figure 4. Power Derating Curve**

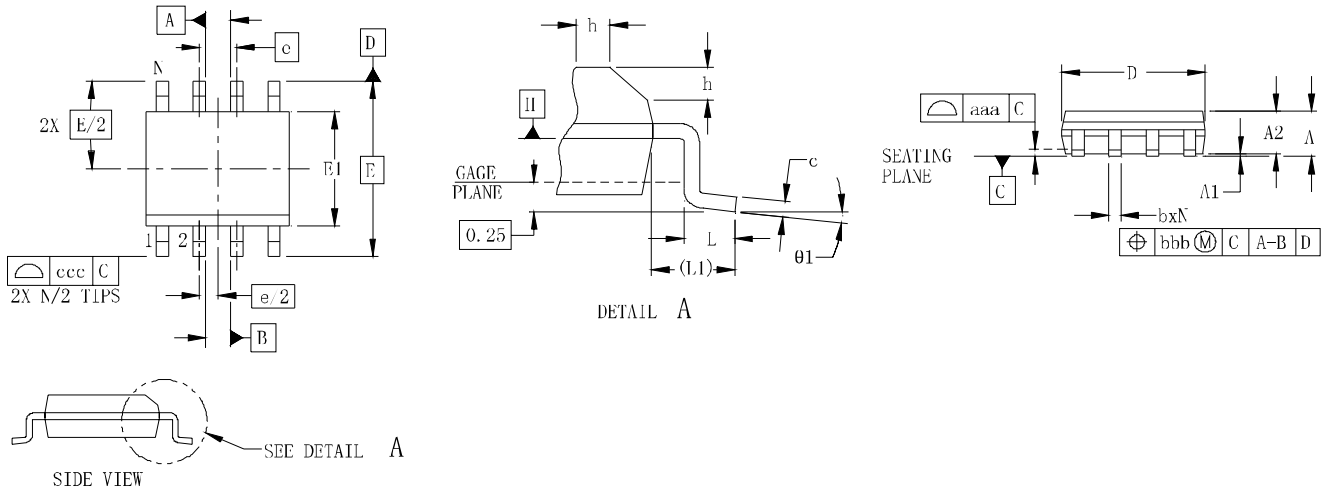


**Figure 5. 8 X 20 $\mu\text{s}$  Pulse Waveform**



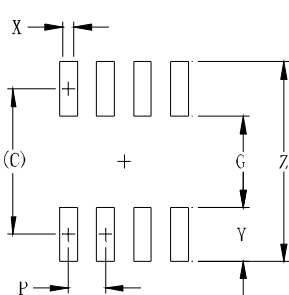
Note: Data is taken with a 10x attenuator  
**Figure 6. ESD Clamping Voltage**  
**8 kV Contact per IEC61000-4-2**

**Package Outline Dimensions (SOP-8)**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.35	1.75	0.053	0.069
A1	0.10	0.25	0.004	0.010
A2	1.25	1.65	0.049	0.065
b	0.31	0.51	0.012	0.020
c	0.17	0.25	0.007	0.010
D	4.80	5.00	0.189	0.197
E1	3.80	4.00	0.150	0.157
E	6.00 BSC		0.236 BSC	
e	1.27 BSC		0.050 BSC	
h	0.25	0.50	0.010	0.020
L	0.40	1.04	0.016	0.041
L1	(1.04)		(0.041)	
N	8		8	
θ1	0°	8°	0°	8°
aaa	0.10		0.004	
bbb	0.25		0.010	
ccc	0.20		0.008	

**Recommended Pad Layout**



Symbol	Dimensions	
	Millimeters	Inches
C	(5.20)	0.205
G	3.00	0.118
P	1.27	0.050
X	0.60	0.024
Y	2.20	0.087
Z	7.40	0.291

**Order Information**

Device	Package	Marking	Carrier	Quantity
GSEQ6B080	SOP-8	LC-6	Tape & Reel	2,500pcs / Reel

For more information, please contact us at: [inquiry@goodarksemi.com](mailto:inquiry@goodarksemi.com)